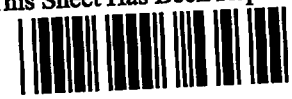
# METHOD OF IMPROVED CAVITY BGA CIRCUIT PACKAGE

Abstract

An improved bonding system (10) is provided in which a metal heat spreader (12) is bonded to semiconductor chip (14). A two adhesive system is used in which a first adhesive (16) demonstrates high bond strength with a second adhesive (18) exhibits high thermal conductivity.

Fig 1

This Sheet Has Been Replaced



THIS SHEET HAS BEEN REPLACED